

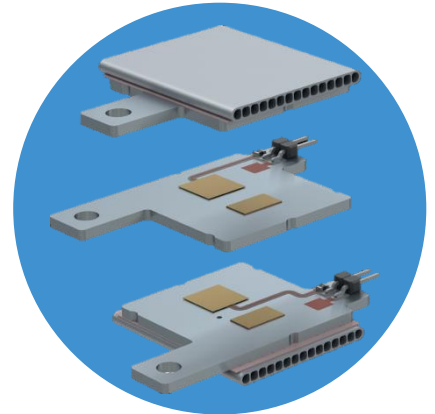
# Fast Facts

## Power Stack

### Double-sided cooling for a MOSFET and 48 V B6 bridge inverter

The Power Stack Technology is an electronic packaging architecture which enables double sided cooling for active semiconductor components.

This brings a reduction in thermal resistance as well as an increase in power density (up to 30 kW). Made with metal substrates and thick film dielectrics, a reliable, cost effective, light weight, small footprint power module is now possible.



### Applications

- Power module with double-sided cooling without wire-bond connections
- Optimised packaging concept for reducing parasitic inductance
- Reduction in thermal resistance due to a larger surface contact area
- Reduction in cost by removing expensive DCB substrates as well as heat spreading baseplates
- Very low inductance design
- Light weight and small footprint

### Technology

- Full B6-Bridge integrated
- 24 MOSFETs
- 2x NTC
- Up to 400 A
- 48 V

